

Title (en)  
SUBSTRATE PROCESSING APPARATUS

Title (de)  
SUBSTRATVERARBEITUNGSVORRICHTUNG

Title (fr)  
APPAREIL DE TRAITEMENT DE SUBSTRAT

Publication  
**EP 4333034 A1 20240306 (EN)**

Application  
**EP 23190731 A 20230810**

Priority  
JP 2022141076 A 20220905

Abstract (en)  
A substrate processing apparatus includes a nozzle that supplies a processing liquid to a substrate, a mover that moves the nozzle between a supply position above a substrate and a waiting position outward of the substrate, a nozzle container that is located at the waiting position and contains the nozzle, a first exhaust flow path that guides a gas in a processing space in which a processing liquid is supplied to a substrate to an exhaust device, and a second exhaust flow path that guides a gas in the nozzle container to the first exhaust flow path.

IPC 8 full level  
**H01L 21/67** (2006.01)

CPC (source: EP US)  
**B05B 12/002** (2013.01 - US); **B05B 13/04** (2013.01 - US); **B05D 1/02** (2013.01 - US); **H01L 21/67051** (2013.01 - EP)

Citation (applicant)  
JP 2017092240 A 20170525 - SCREEN HOLDINGS CO LTD

Citation (search report)

- [XA] US 2015090305 A1 20150402 - WAKIYAMA TERUFUMI [JP], et al
- [AD] JP 2017092240 A 20170525 - SCREEN HOLDINGS CO LTD

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC ME MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA

Designated validation state (EPC)  
KH MA MD TN

DOCDB simple family (publication)  
**EP 4333034 A1 20240306**; JP 2024036245 A 20240315; US 2024075489 A1 20240307

DOCDB simple family (application)  
**EP 23190731 A 20230810**; JP 2022141076 A 20220905; US 202318366252 A 20230807